

ABSTRACT

The present invention relates to a polyimide metal laminate comprising a polyimide resin formed on a metal foil, wherein the polyimide resin does not cause the peeling of not less than 100 μm in the polyimide resin and/or at an interface between the polyimide resin and the metal foil when the polyimide resin is heated in an oven at an atmospheric temperature of from 340 to 360°C for 5 to 10 minutes, the coefficient of humidity expansion at 32° is from 1 to 20 ppm/%RH, and an average value of the etching rate by a 50 wt % aqueous solution of potassium hydroxide at 80°C is not less than 1.0 $\mu\text{m}/\text{min}$.

According to the present invention, it is possible to provide a polyimide metal laminate in which heat resistance is good, the dimensional stability is superior and the etching processing by an aqueous alkaline solution is enabled.